21th IEEE/ACM International Workshop on System-Level Interconnect Prediction (SLIP 2019)

www.SLIPonline.org

Co-located with ACM/IEEE Design Automation Conference

June 2, 2019

Las Vegas Convention Center, Las Vegas, NV

Co-sponsored by the ACM SIGDA and the IEEE Computer Society

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The general technical scope of the workshop is the design, analysis, and optimization of interconnect and communication fabrics in electronic systems. **A special emphasis is placed this year on predictive technologies and machine learning applications.** The organizing committee invites original contributions in the form of papers, tutorials, panels, special session, and posters. We accept papers based on novelty and contributions to the advancement of the field. The accepted papers will be published in the ACM and IEEE digital libraries.

Technical topics include but are not limited to:

- Learning and predictive models for optimizing interconnect at various IC and system design stages
- System-level design for FPGAs, NoCs, reconfigurable systems
- Design, analysis, and (co)optimization of power and clock networks
- Topologies and fabrics of multi- and many-core architectures
- Power consumption of interconnects
- System level reliability, aging, and thermal issues
- Security-aware power/clock delivery and interconnect design
- Design-for-manufacturing (DFM) and yield techniques for interconnects
- High speed chip-to-chip interconnect
- Design and analysis of chip-package interfaces
- 3D interconnect design and prediction
- Applications of interconnects to social, genetic, and biological systems
- Emerging interconnect technologies in machine learning platforms & chips

Submission:

We invite authors to submit papers of 4 to 8 pages, double-columned, 9pt or 10pt font in ACM proceedings format available at https://www.acm.org/publications/proceedings-template

To permit double blind review, all papers must remove author information (submissions with author information will be rejected). Authors should submit papers electronically: https://easychair.org/conferences/?conf=slip2019

Student Awards:

Student Awards may be available. Please check the website for more information.

Format:

The workshop includes keynotes, regular paper sessions, interactive panels, tutorials, invited talks, and interactive poster sessions. Our program includes lunch and refreshments, and potentially a social dinner with fun elements.

Important Dates:

Abstract Registration: Mar 7, 2019
Paper Submission: Mar 14, 2019
Author Notification: April 19, 2019
Final Version Upload: April 28, 2019